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With the rise of the Internet of Things (IoT), where over 50 billion devices and applications, from smartphones to sensors, are expected to be in use by 2020, it is important for businesses to innovate continuously in an increasingly connected world.

UTAC - an OSAT (Outsourced Semiconductor Assembly & Test) partner to fabless companies, integrated device manufacturers and wafer foundries, sees a strong demand in new technologies such as Cu Clip, CMOS image sensors and MEMS for 2019.

To keep up with technology advancements, we constantly invest in our R&D. For example, as more complicated structures are in demand for Cu Clip technology, we have increased our R&D investment to meet this positive trend.

Serving in the automotive and industrial sectors, it is crucial to have reliable and quality products. We have automated our processes, customised and redesigned our machines to create a smart factory, for increased productivity, safety and zero defects.

In the past year, UTAC has achieved many key milestones, including our emergence from financial restructuring and hitting record shipments at our Thailand facility. We look forward to continuing the momentum by further investing and expanding, as well as putting in more capacity to ramp up ahead of demand.



Dr John Nelson,
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